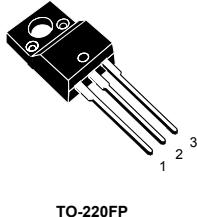


## N-channel 800 V, 0.95 $\Omega$ typ., 6.5 A MDmesh Power MOSFET in a TO-220FP package

### Features



Order code	$V_{DS}$	$R_{DS(on)}$ max.	$I_D$
STF7NM80	800 V	1.05 $\Omega$	6.5 A

- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance

### Applications

- Switching applications

### Description

This N-channel Power MOSFET is developed using STMicroelectronics' revolutionary MDmesh technology, which associates the multiple drain process with the company's PowerMESH horizontal layout. This device offers extremely low on-resistance, high dv/dt, and excellent avalanche characteristics. Using STMicroelectronics's proprietary strip technique, this Power MOSFET boasts an overall dynamic performance that is superior to similar products on the market.



#### Product status link

[STF7NM80](#)

#### Product summary

Order code	STF7NM80
Marking	F7NM80
Package	TO-220FP
Packing	Tube

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	800	V
$V_{GS}$	Gate-source voltage	$\pm 30$	V
$I_D$ <sup>(1)</sup>	Drain current (continuous) at $T_C = 25^\circ\text{C}$	6.5	A
	Drain current (continuous) at $T_C = 100^\circ\text{C}$	4	
$I_{DM}^{(1)(2)}$	Drain current (pulsed)	26	A
$P_{TOT}$	Total power dissipation at $T_C = 25^\circ\text{C}$	25	W
$V_{ISO}$	Insulation withstand voltage (RMS) from all three leads to external heat sink ( $t = 1\text{ s}$ , $T_C = 25^\circ\text{C}$ )	2.5	kV
$T_{stg}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature range		$^\circ\text{C}$

1. This value is limited by maximum junction temperature.
2. Pulse width is limited by safe operating area.

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case	5	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Thermal resistance, junction-to-ambient	62.5	$^\circ\text{C}/\text{W}$

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AS}$	Avalanche current, repetitive or non-repetitive (pulse width limited by $T_J$ max.)	1	A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25^\circ\text{C}$ , $I_D = I_{AS}$ , $V_{DD} = 50\text{ V}$ )	240	mJ

## 2 Electrical characteristics

$T_C = 25^\circ\text{C}$  unless otherwise specified.

**Table 4. On/off states**

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	800			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 800 \text{ V}$			10	$\mu\text{A}$
		$V_{GS} = 0 \text{ V}, V_{DS} = 800 \text{ V}, T_C = 125^\circ\text{C}^{(1)}$			100	
$I_{\text{GSS}}$	Gate body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 30 \text{ V}$			$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	3	4	5	V
$R_{\text{DS}(\text{on})}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 3.25 \text{ A}$		0.95	1.05	$\Omega$

1. Specified by design, not tested in production.

**Table 5. Dynamic**

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$C_{\text{iss}}$	Input capacitance	$V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	620	-	pF
$C_{\text{oss}}$	Output capacitance		-	460	-	pF
$C_{\text{rss}}$	Reverse transfer capacitance		-	15	-	pF
$R_g$	Gate input resistance	$f = 1 \text{ MHz}$ open drain	-	7	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 640 \text{ V}, I_D = 6.5 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$ (see Figure 13. Test circuit for gate charge behavior)	-	18	-	nC
$Q_{\text{gs}}$	Gate-source charge		-	4	-	nC
$Q_{\text{gd}}$	Gate-drain charge		-	11	-	nC

**Table 6. Switching times**

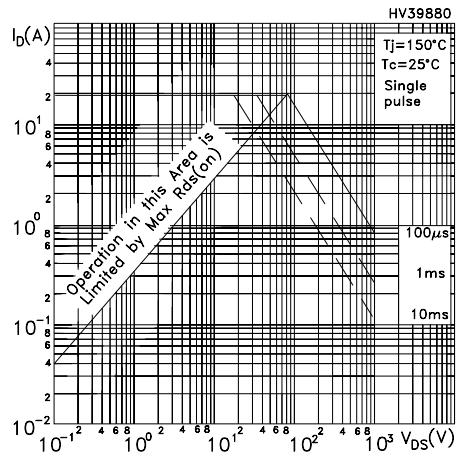
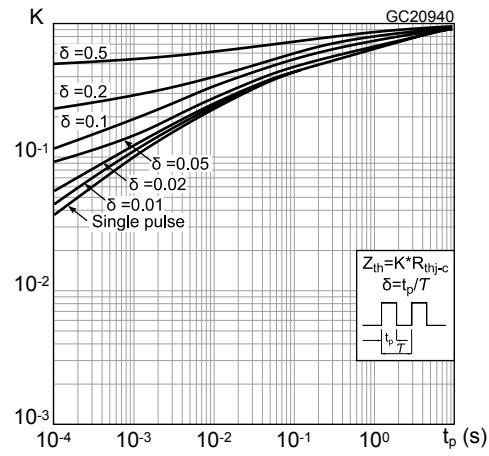
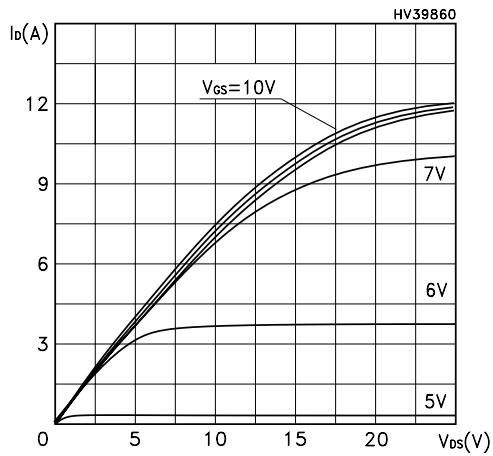
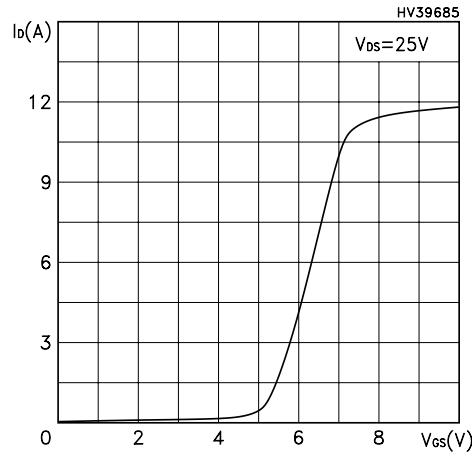
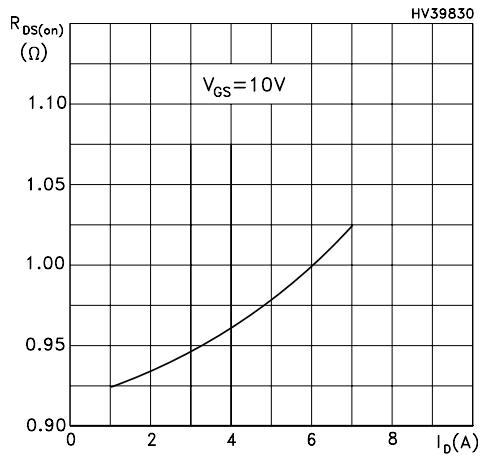
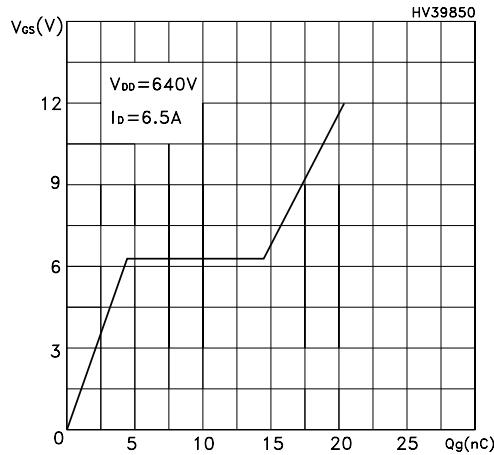
Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$t_{\text{d}(\text{on})}$	Turn-on delay time	$V_{DD} = 400 \text{ V}, I_D = 3.25 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	20	-	ns
$t_r$	Rise time		-	8	-	ns
$t_{\text{d}(\text{off})}$	Turn-off delay time		-	35	-	ns
$t_f$	Fall time	(see Figure 12. Test circuit for resistive load switching times and Figure 17. Switching time waveform)	-	10	-	ns

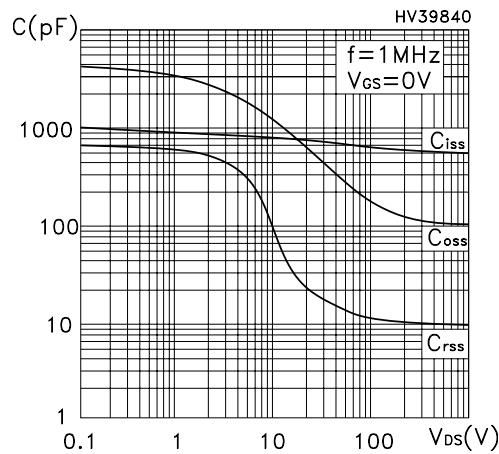
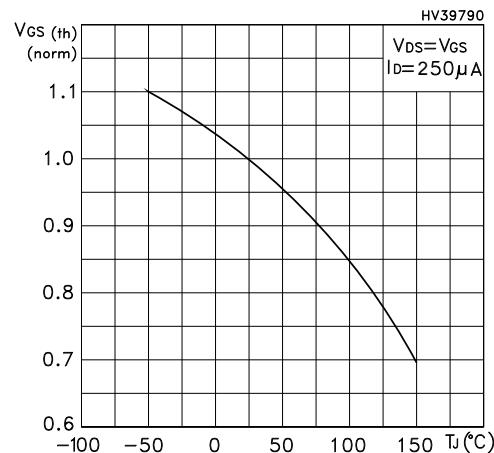
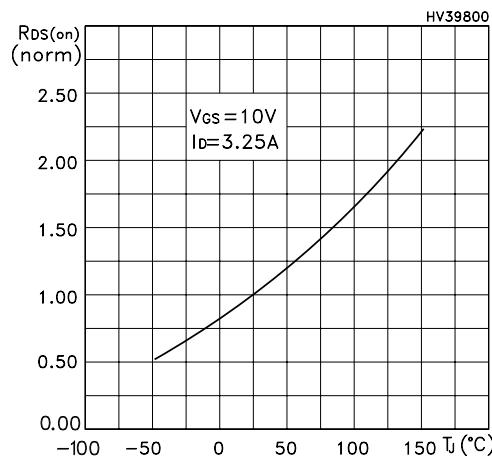
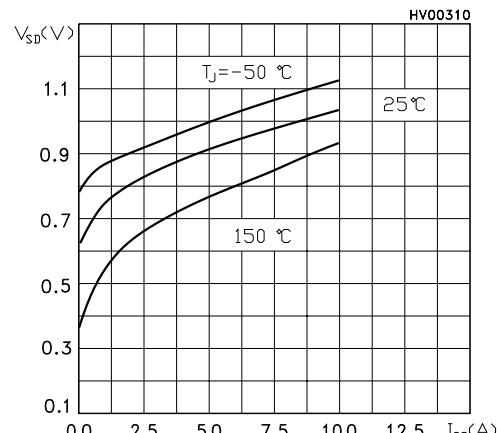
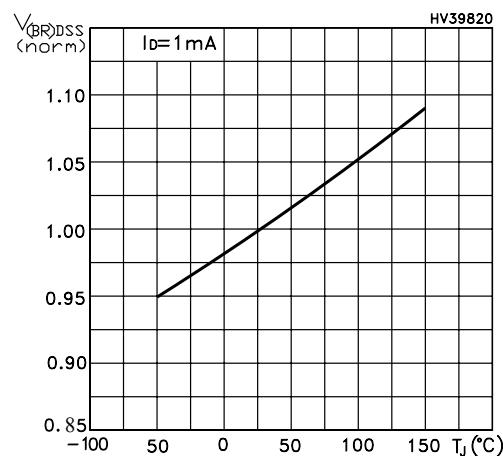
Table 7. Source-drain diode

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		6.5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		26	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 6.5 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.3	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 6.5 \text{ A}, dI/dt = 100 \text{ V}$	-	460		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 50 \text{ V}$ (see Figure 14. Test circuit for inductive load switching and diode recovery times)	-	4		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	$I_{SD} = 6.5 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	-	17		A
$t_{rr}$	Reverse recovery time	$V_{DD} = 50 \text{ V}$ (see Figure 14. Test circuit for inductive load switching and diode recovery times)	-	680		ns
$Q_{rr}$	Reverse recovery charge		-	6		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	17		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

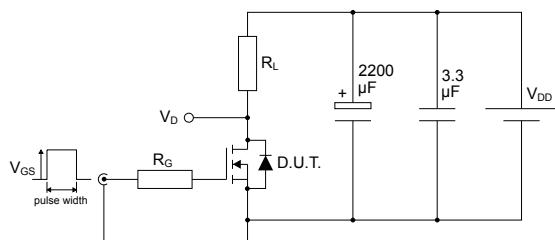
## 2.1 Electrical characteristics (curves)

**Figure 1. Safe operating area**

**Figure 2. Thermal impedance**

**Figure 3. Output characteristics**

**Figure 4. Transfer characteristics**

**Figure 5. Static drain-source on-resistance**

**Figure 6. Gate charge vs gate-source voltage**


**Figure 7. Capacitance variations**

**Figure 8. Normalized gate threshold voltage vs temperature**

**Figure 9. Normalized on-resistance vs temperature**

**Figure 10. Source-drain diode forward characteristics**

**Figure 11. Normalized  $V_{(BR)DSS}$  vs temperature**


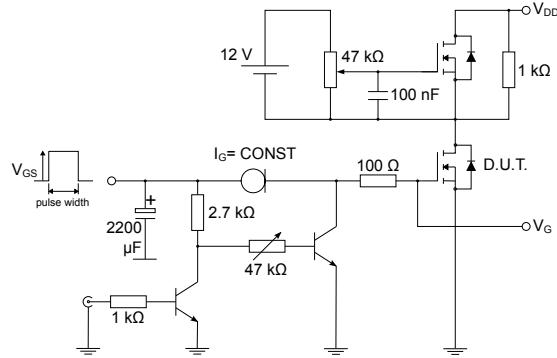
### 3 Test circuits

**Figure 12. Test circuit for resistive load switching times**



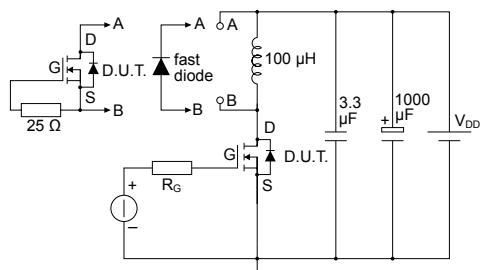
AM01468v1

**Figure 13. Test circuit for gate charge behavior**



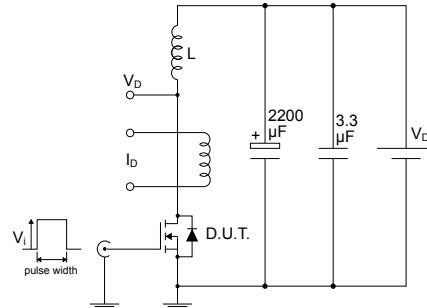
AM01469v1

**Figure 14. Test circuit for inductive load switching and diode recovery times**



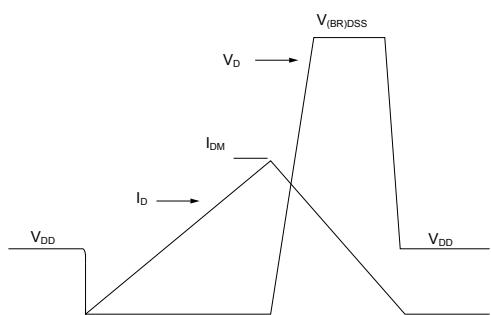
AM01470v1

**Figure 15. Unclamped inductive load test circuit**



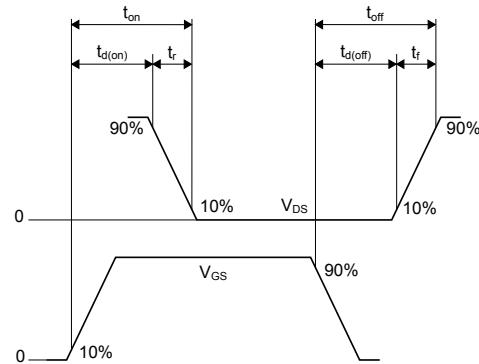
AM01471v1

**Figure 16. Unclamped inductive waveform**



AM01472v1

**Figure 17. Switching time waveform**



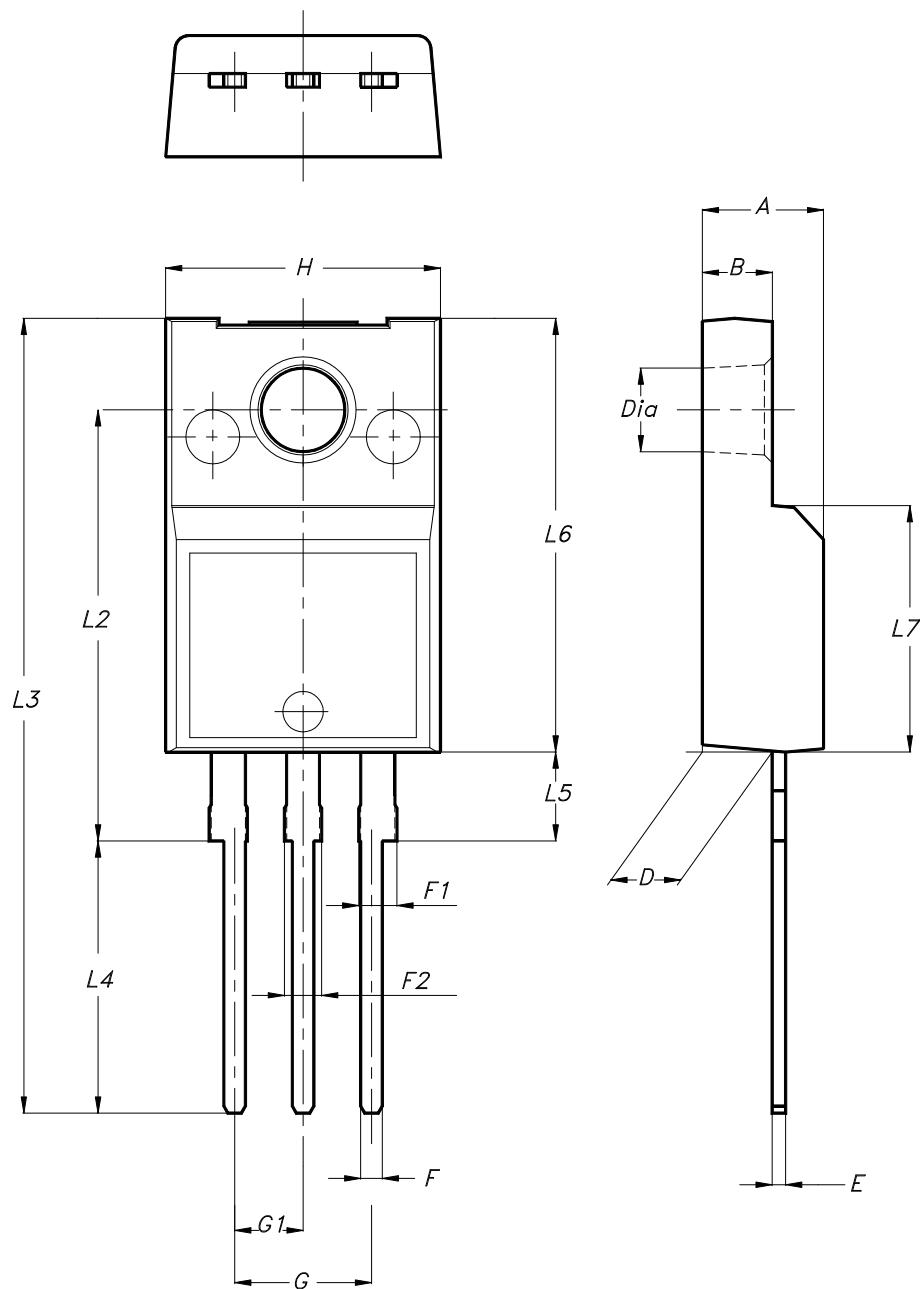
AM01473v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-220FP type B package information

Figure 18. TO-220FP type B package outline



**Table 8. TO-220FP type B package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.70
F	0.75		1.00
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.20
G1	2.40		2.70
H	10.00		10.40
L2		16.00	
L3	28.60		30.60
L4	9.80		10.60
L5	2.90		3.60
L6	15.90		16.40
L7	9.00		9.30
Dia	3.00		3.20

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
30-May-2023	1	First release. The part number STF7NM80 was previously inserted in the DS4854.

## Contents

<b>1</b>	<b>Electrical ratings</b>	<b>2</b>
<b>2</b>	<b>Electrical characteristics</b>	<b>3</b>
2.1	Electrical characteristics (curves)	5
<b>3</b>	<b>Test circuits</b>	<b>7</b>
<b>4</b>	<b>Package information</b>	<b>8</b>
4.1	TO-220FP type B package information	8
	<b>Revision history</b>	<b>10</b>

**IMPORTANT NOTICE – READ CAREFULLY**

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgment.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, refer to [www.st.com/trademarks](http://www.st.com/trademarks). All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2023 STMicroelectronics – All rights reserved